Product End-of-Life Disassembly Instructions

Product Category: Other Products
Marketing Name / Model [List multiple models if applicable.]
AG781B: HP StorageWorks SAN Virtualization Services Platform Hardware Bundle
AG781A: HP EVA-VS

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm **One main board and two power supply boards**	3
Batteries	All types including standard alkaline and lithium coin or button style batteries **From main system pcba**	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		1
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips screwdrivers	#2
Flat blade screwdriver	

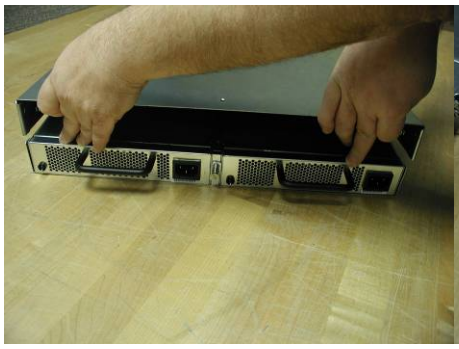
3.0 Product Disassembly Process

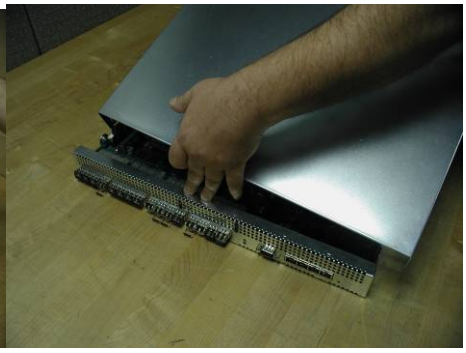
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the plastic bezel using a flat blade screwdriver
2. Remove steel cover by removing the screws (see photos on the next page) with a phillips screwdriver in the top cover that attach it to the chassis. Lift the cover at the power supply end until it just clears the power supplies. Pull the cover straight out towards the power supplies until the front of the cover just clears the chassis. Lift the front of the cover straight up until it clears the chassis and can be removed.
3. Unlock the power supply latch using a flat blade screwdriver (See photos on the next page) and pull out the two power cooling modules
4. Pull out the lithium coin battery from the holder on the pcba at location XB2E0 (See photos on the next page).
5. Remove all the pcba mounting screws using a phillips screwdriver
6. Remove the four mounting screws for the cpu heat sink and remove the heat sink.
7. Remove the cover from each power cooling module (See photos on the next page) by removing the two mounting screws using a phillips screwdriver
8. Remove each power supply by removing the phillips mounting screws and disconnecting the cable assemblies.
9. Each power supply consists of one pcba.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Step 2: Cover removal:



Step 3: Power Supply Latch


Step 4: Battery location: